Product / Package Information

Package	LFCSP - Punch
Body Size (mm)	12 X 12 X 0.85 (6.9 EP)
LeadCount	100
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.52E-01	86.9	869100	39.46	394600
Thermosets	Epoxy & Phenol Resin	Proprietary	2.23E-02	12.8	127800	5.80	58025
Other inorganic materials	Carbon black	1333-86-4	5.41E-04	0.3	3100	0.14	1408
Subtotal			1.74E-01	100.00	1000000	45.40	454033

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.76 E-01	96.40	963989	45.81	458099
Copper & its alloys	Nickel	7440-02-0	4.57 E-03	2.50	25006	1.19	11883
Copper & its alloys	Silicon	7440-21-3	1.10 E-03	0.60	6004	0.29	2853
Copper & its alloys	Zinc	7440-66-6	9.13 E-04	0.50	5001	0.24	2377
Subtotal			1.83 E-01	100.00	1000000	47.52	475212

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.14 E-03	100.0	1000000	0.30	2957

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.36 E-03	100.0	1000000	1.39	13947

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.33 E-03	100.0	1000000	1.13	11258

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.41 E-02	100.0	1000000	3.66	36641

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.68 E-03	73.40	734000	0.44	4368
Thermoset	Epoxy Resin	Proprietary	4.19 E-04	18.35	183500	0.11	1092
Other inorganic materials	Metal oxide	Proprietary	6.29 E-05	2.75	27500	0.02	164
Others	Curing and hardening agent	Proprietary	6.29 E-05	2.75	27500	0.02	164
Other organic materials	Gamma Butyrolactone	96-48-0	6.29 E-05	2.75	27500	0.02	164
Subtotal			2.29 E-03	100.0	1000000	0.60	5951

			Weight (g)			**Percentage (%)**	**PPM**
Package Totals			**3.84 E-01**			**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary